

(19)



JAPANESE PATENT OFFICE

PATENT ABSTRACTS OF JAPAN

(11) Publication number: **04327396 A**

(43) Date of publication of application: **16.11.1992**

(51) Int. Cl. **B23K 35/26**
C22C 11/06

(21) Application number: **03122885**
(22) Date of filing: **26.04.1991**

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(54) HIGH-TEMPERATURE SOLDER

(57) Abstract:

PURPOSE: To provide the high-temp. solder which obviates the remelting of the soldered part in a hybrid IC at the time of molding the hybrid IC with a resin and assembling the IC into electronic appliances and does not generate the silver suffering in circuits at the time

of soldering.

CONSTITUTION: This high-temp. solder consists essentially of Pb, is added with 8 to 14wt.% Sn and 8 to 10wt.% Sb and is added with ≤ 2 wt.% Ag in order to prevent the silver suffering. This solder has $\geq 230^{\circ}\text{C}$ solidus line temp. and $\leq 260^{\circ}\text{C}$ soldering temp. and is, therefore, suitable for double deposition of soldering and has less thermal influence on parts.

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